



IC Packages, Assembly & Prototype Services

Press Release

Contact: Steve Swendrowski
Phone: 1(858)674-4676

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Quik-Pak Awarded Large Mil Spec Contract

San Diego, CA, April 24, 2008- Quik-Pak, a division of Delphon Industries, announced today that it has been awarded a large contract for wafer dicing, pick-and-place, and visual inspection completed to Military Specification 883. This Military Specification establishes uniform methods, controls, and procedures for testing microelectronic devices suitable for use within Military and Aerospace electronic systems including basic environmental tests to determine resistance to deleterious effects of natural elements and conditions surrounding military and space operations; mechanical and electrical tests; workmanship and training procedures; and such other controls and constraints as have been deemed necessary to ensure a uniform level of quality and reliability suitable to the intended applications of those devices.

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"Quik-Pak has made a great deal of changes to its operations over the last year, including expanding its facility, offering additional services, adding more equipment and achieving ISO certification. These improvements have made it possible for us to accommodate larger contracts like this," says Steve Swendrowski, General Manager of Quik-Pak.

Background:

Quik-Pak, a division of Delphon Industries, offers IC packages, assembly and prototype services. The company specializes in open-cavity plastic packages and assembly in 24 hours or less. A limitless array of open-cavity packages is available with no minimum quantity and can be provided as part of a turn-key assembly solution along with wafer dicing, die/wire bonding, remolding and marking/branding. Custom assembly services are also offered for ceramic packages, chip-on-board, stacked die, MEMS, etc. Quik-Pak's unique offerings deliver faster time to market and reduced prototype costs for new devices, while providing excellent flexibility, quality and customer service.

About the Parent Company:

Quik-Pak is a division of Delphon Industries, LLC. Delphon's mission is to provide materials and services for the shipping, processing and packaging of high value technology and medical components. Headquartered in Hayward, California, CEO Jeanne

Beacham has aggressively positioned Delphon to take advantage of changes within the industries the company serves.

With Divisions Quik-Pak, Gel-Pak, TouchMark and UltraTape along with a worldwide sales and distribution network, Delphon Industries serves a wide range of markets including the Semiconductor, medical device, Opto-electronics, automotive, MEMS, and defense industries. www.delphon.com.

For further information:

CONTACT: Jeanne Beacham, CEO 1(510)576-2220

Steve Swendroski, General Manager 1(858)674-4676

Or visit: www.icproto.com